

## Strain Gage Adhesive



### OTHER ACCESSORIES USED IN AN M-BOND GA-61 INSTALLATION:

- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

### DESCRIPTION

Two-component, partially filled, 100%-solids epoxy adhesive for general-purpose stress analysis. Very high viscosity. Widely used to fill irregular surfaces and to anchor leadwires.

Forms a very hard, chemical-resistant material when fully cured. Glueline thickness is generally <0.002 in [0.05 mm].

### CHARACTERISTICS

#### Operating Temperature Range:

**Short Term:** -100° to +600°F [-75° to +315°C].

**Long Term:** -100° to +500°F [-75° to +260°C].

#### Elongation Capabilities:

1% at -100°F [-75°C];

2% at +75°F [+24°C];

1% at +500°F [+260°C].

#### Shelf Life:

6 months minimum at +75°F [+24°C]; refrigeration recommended.

#### Pot Life:

10 hours at +75°F [+24°C]; increased by refrigeration, indefinite by freezing.

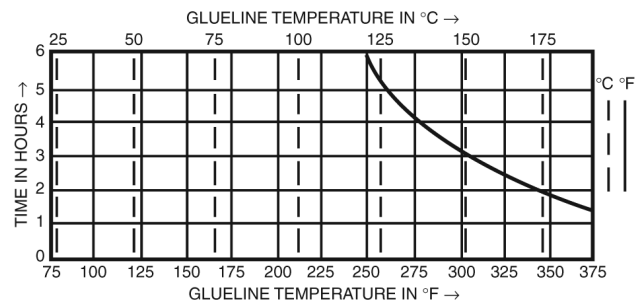
#### Clamping Pressure:

10 to 30 psi [70 to 200 kN/m<sup>2</sup>].

#### Cure Requirements:

**Elevated-Temperature Cure Required.**

**Recommended Postcure:** 1 hour at 50°F [30°C] above maximum operating temperature not to exceed +600°F [+315°C].



### PACKAGING

#### Kit:

3 jars [10 g ea] Resin

3 jars [5 g ea] Hardener

3 stirring rods

**References:** Instruction Bulletin B-128, "Strain Gage Applications with M-Bond GA-61 Adhesive", included in each kit.

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